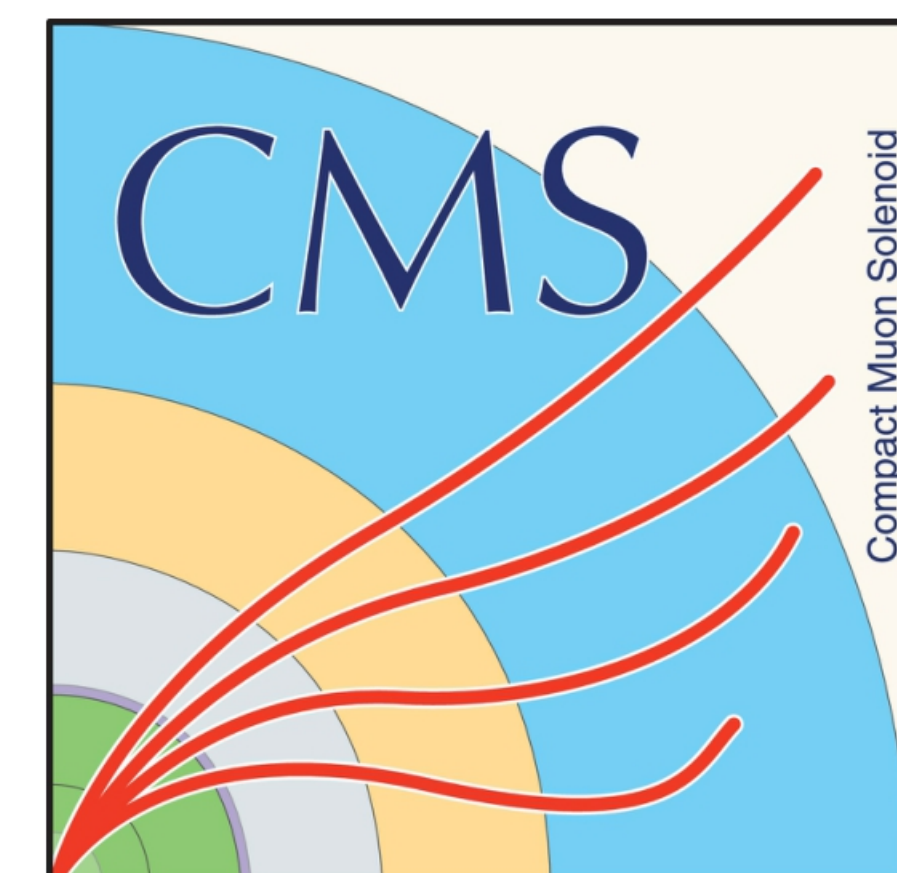




# Commissioning of a Burn-In Setup for PS and 2S Detector Modules for the Upgrade of the CMS Outer Tracker



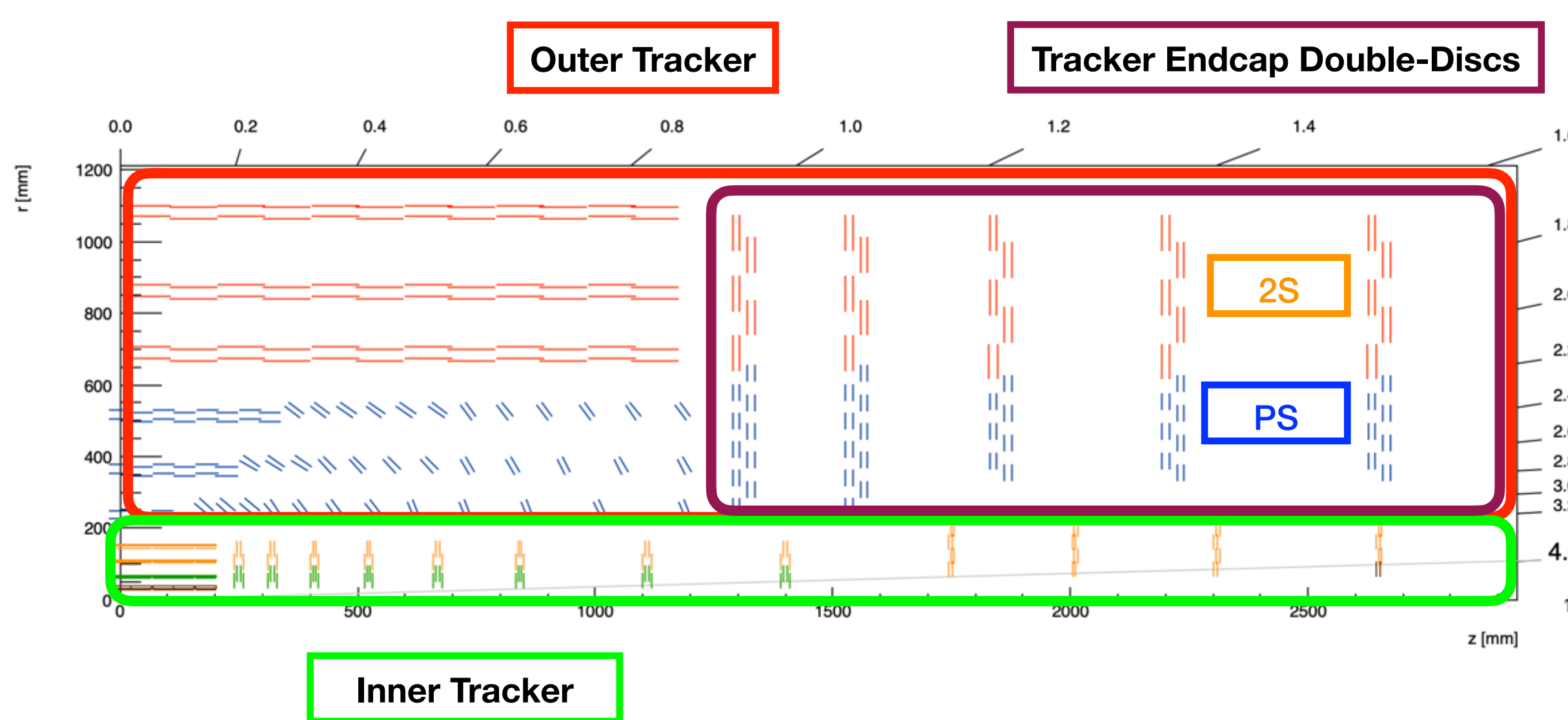
Ana Ventura Barroso on behalf of the CMS Collaboration

## High Luminosity LHC

- Higher radiation levels, up to  $1.1 \times 10^{15} n_{eq} \times cm^{-2}$  in the Outer Tracker
- Larger pileup, 140 and 200 expected, in comparison with the current 60
- Higher L1 rates, from the current  $\sim 110$  kHz to 750 kHz

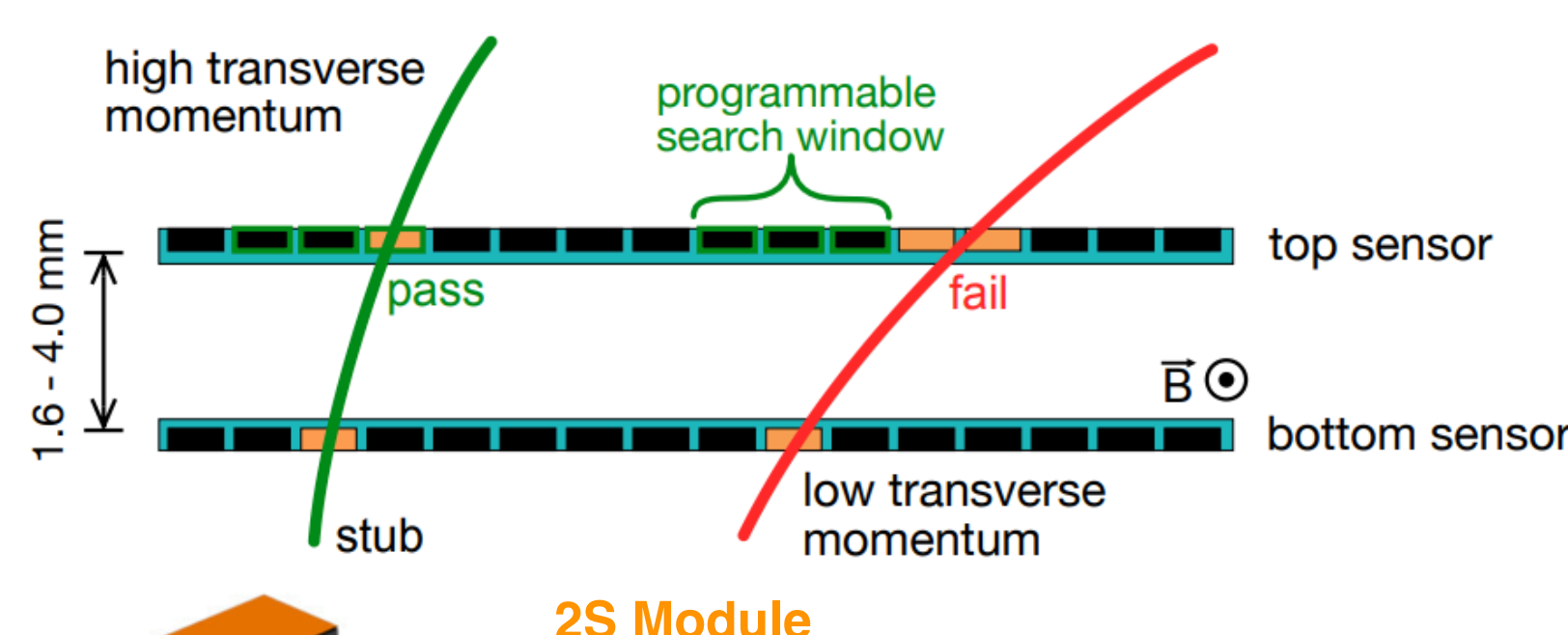
## The Phase-2 CMS Tracker<sup>[1]</sup>

- Radiation tolerant - higher granularity - less material
- Tracks in hardware trigger (L1) making use of Outer Tracker information
- Coverage up to  $|\eta| = 4$



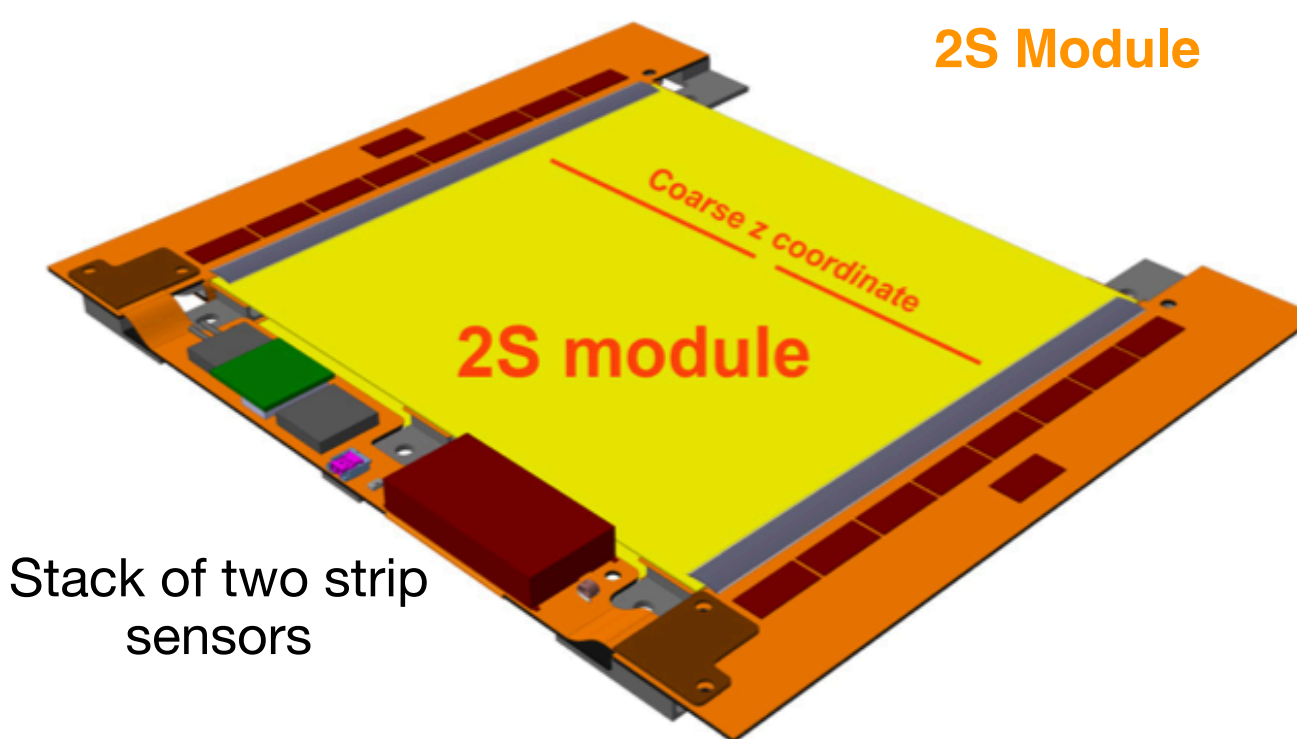
[1]: The Phase-2 Upgrade of the CMS tracker. Technical Design Report. CMS-TDR-14

## Transverse Momentum Discrimination



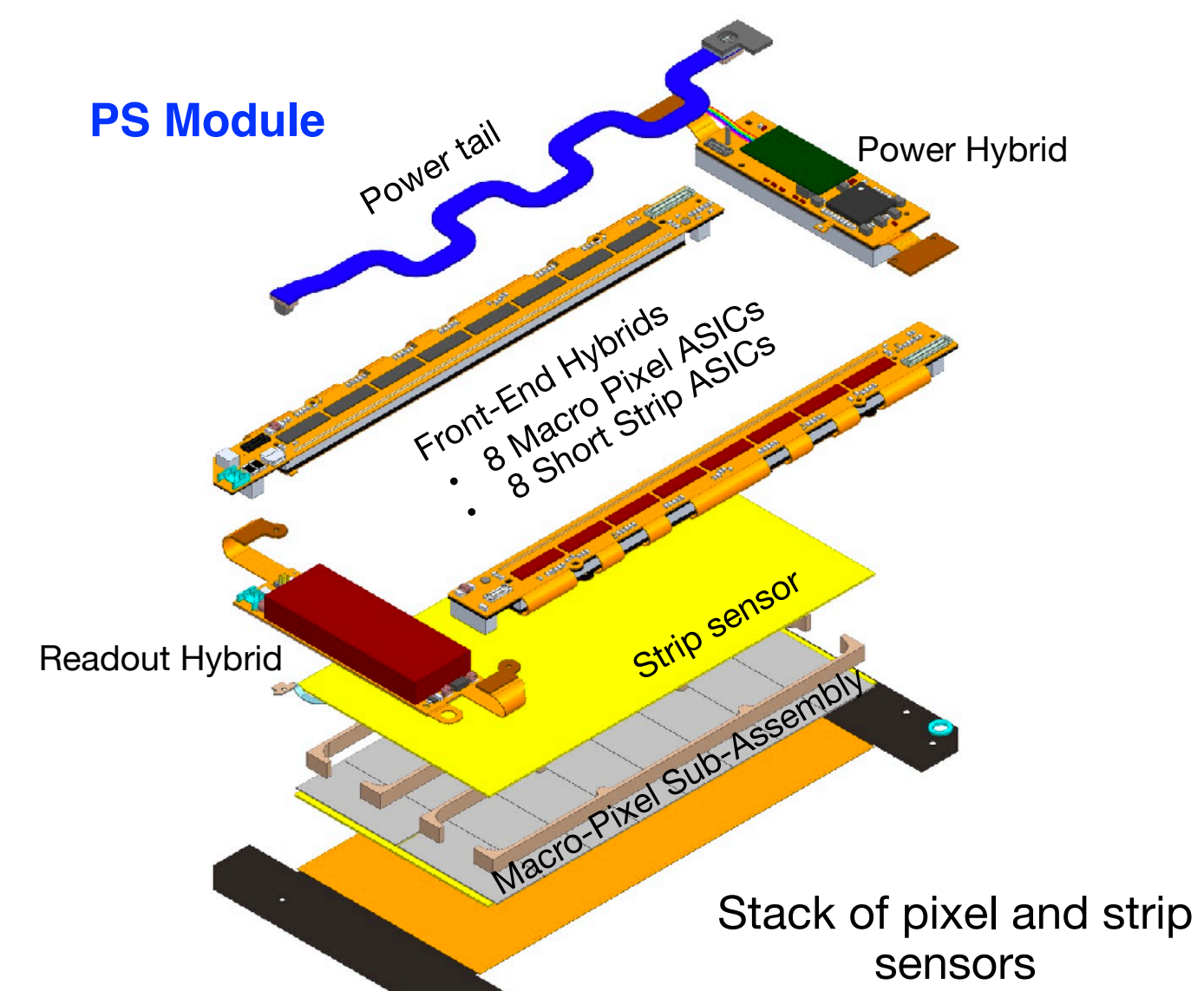
Based on the correlation of the signals within a programmable search window

- Rejection of low transverse momentum particles



Stack of two strip sensors

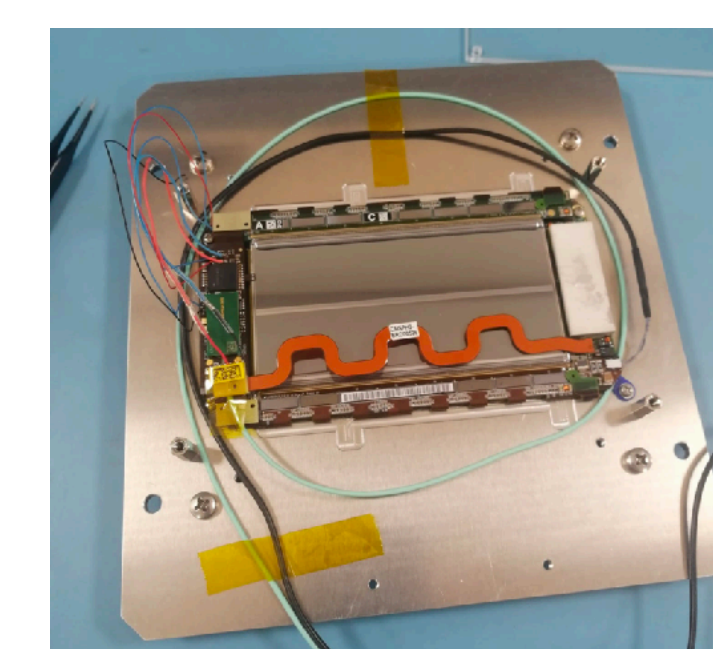
$P_T$  discriminating detector modules



Stack of pixel and strip sensors

## At DESY

- Module Production
  - 1120 PS modules at DESY
- Burn-in test
  - DESY PS modules and 800 2S modules from Aachen
- Dee (half disc) integration and 5 Double-Discs assembly
  - 2S modules coming from Aachen and KIT
- Tracker Endcap Double-Discs assembly and integration will be done at CERN



Modules and connectors are delicate. To avoid handling them during the different production and test steps

- Carrier plate

## Burn-in test

Final test for module qualification to certify that a module is good for integration

### Why:

- Modules quality control needed
  - Ensure operation at operating temperatures ( $\sim 35^\circ C$ )
  - Ensure long term operation
  - Ensure correct functionality of module after warmup and cooldown cycles

### How:

- Thermal cycles from room temperature to operating temperature
- I-V measurement in warm and in cold
- Noise measurements before the test, after the first cool down and at the end of the test

### Specifications:

- 24h test with 5/6 cycles
- 10 modules per setup in parallel
- Running unattended

$\sim 2000$  modules to be tested

Different flavour (2S and PS)

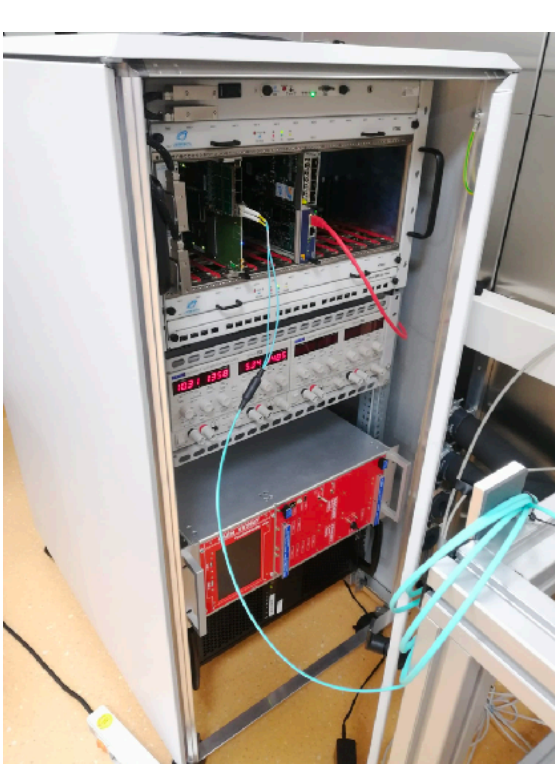
At DESY we will have 2 burn-in setups

## System overview



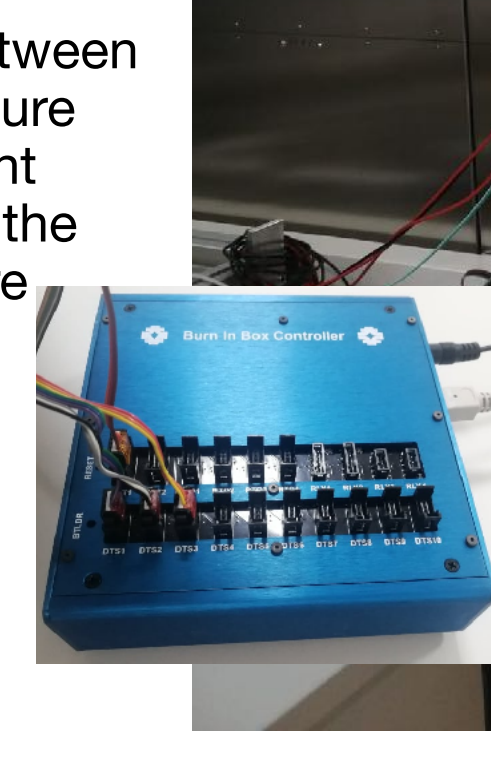
### Chiller

- Unistat Hubber Pilot One



### Rack

- Power supplies
- Read-out system
- FC7: FPGA-based circuit board



### Controller Board

- Interface between the temperature and dew point sensors and the DAQ software



### Fridge: Passive cooling unit

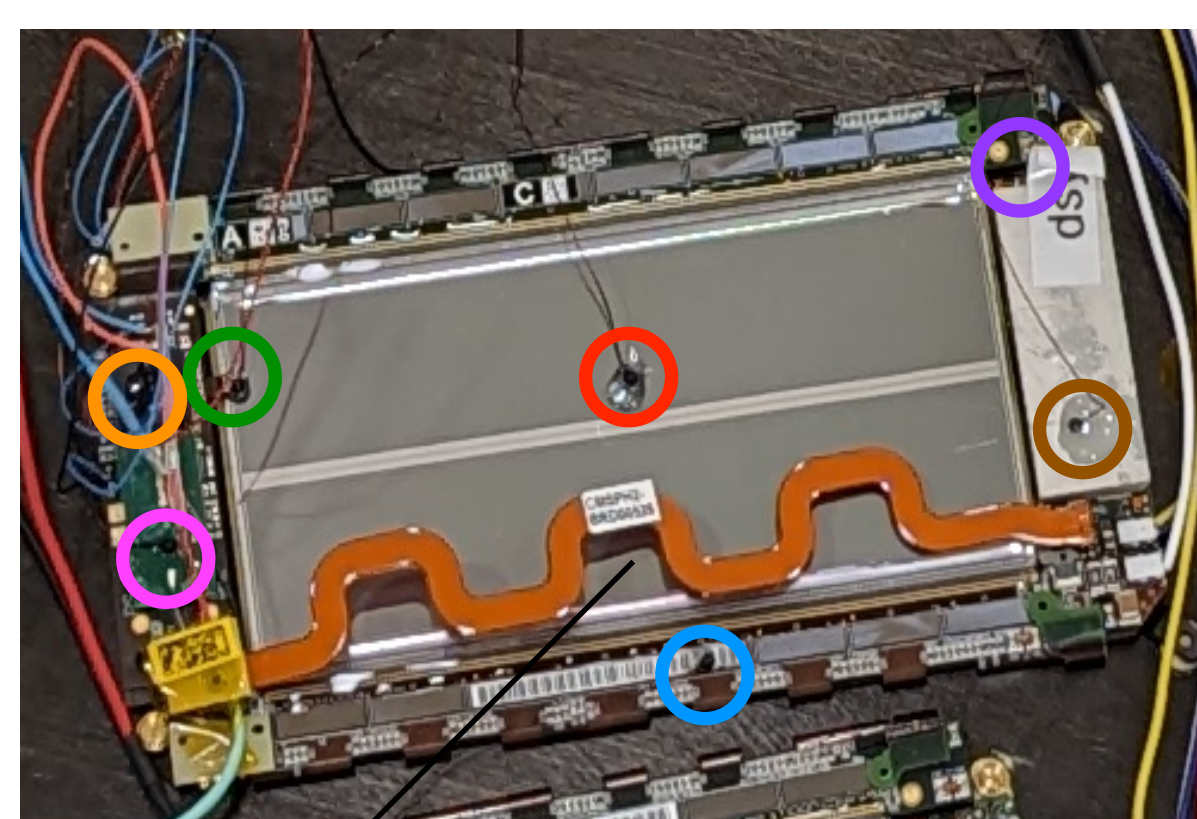
- Carrier plate support
- Cooling pipes connected to the chiller
- Temperature sensors
- Dew point sensor
- Magnetic interlock
- Dry air supply

## Temperature studies

Studies performed during commissioning for understanding the distribution of cooling through the module

- 7 thermistors attached to different positions
- Check homogeneity through the module, thermal contact and hot spots

- S1: on top of the optical link module (VTRx+), located in the Readout Hybrid
- S2: on top of the DCDC converter in the Power Hybrid
- S3: on the low-power Gigabit Transceiver (lpGBT), located in the Readout Hybrid
- S4: on one of the Front-End Hybrids
- S5: next to one of the insert pins
- S6: in the edge of the the Strip sensor, next to temperature sensor in the hybrid
- S7: in the middle of the Strip sensor



### Observations

Highest temperature at S1 (VTRx) when module is powered. High temperature in S2 and S3 when powered and configured

- Non-optimal thermal contact with the carrier plate

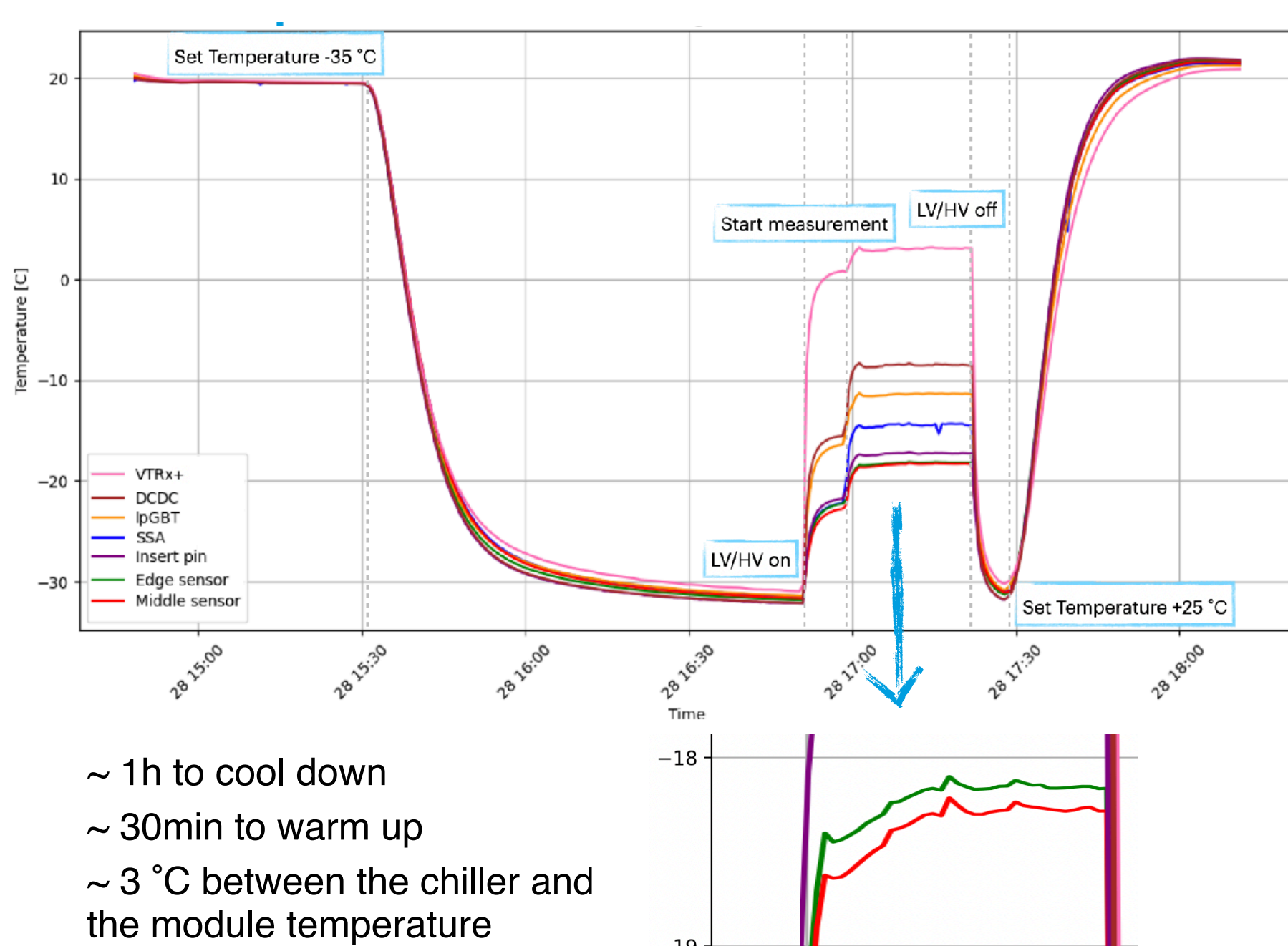
S4 big increase when starting a measurement

- Localized power dissipation during configuration and readout

S5 expected to be the coolest (proximity to module's thermal contact)

S6 and S7 almost same temperature

- Good homogeneity in the Strip sensor



- $\sim 1$ h to cool down
- $\sim 30$ min to warm up
- $\sim 3^\circ C$  between the chiller and the module temperature

## Noise studies

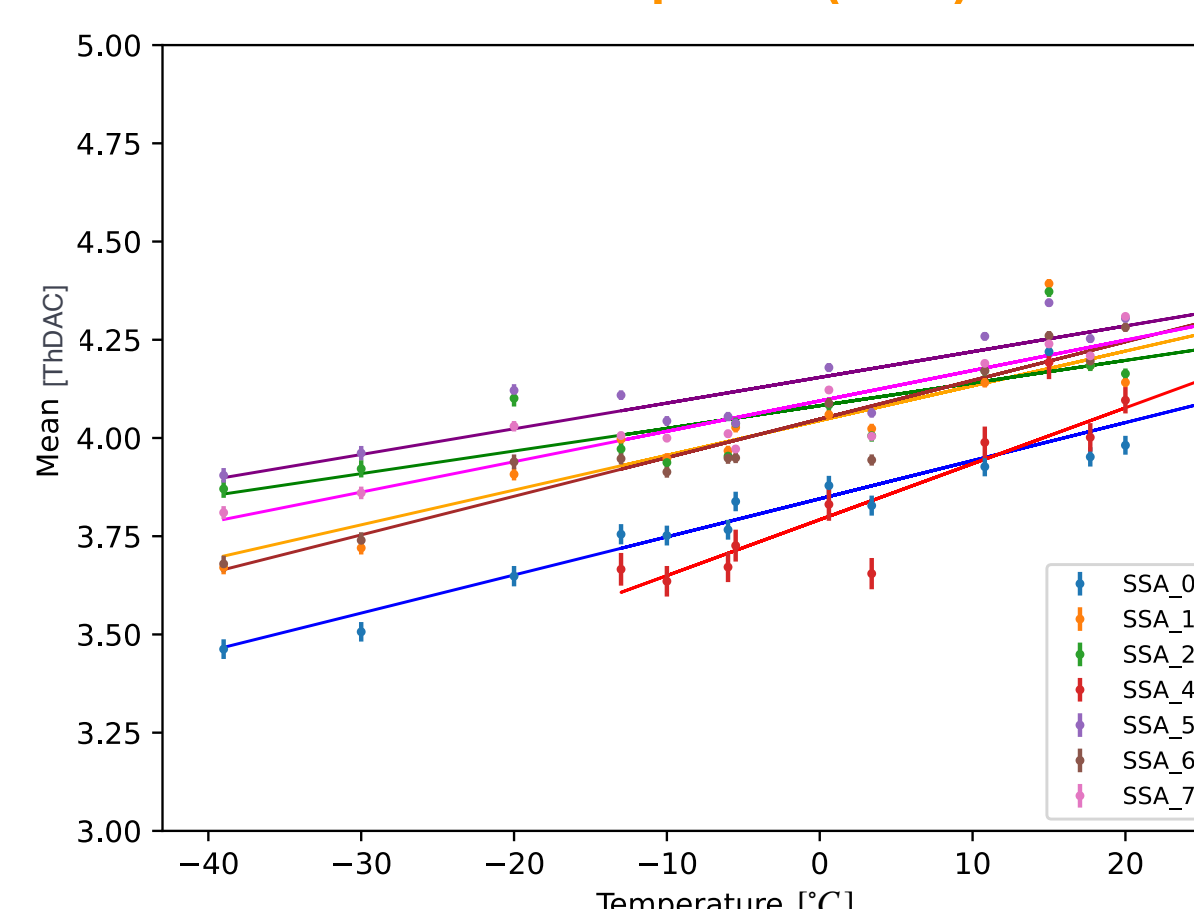
Noise is a key measure of the quality and performance of each individual Front-End channel

- Used to optimize the design and operation of the module

Noise level targeted

- Around 4 ThDAC for Strips
- Between 2 and 3 ThDAC for Pixels

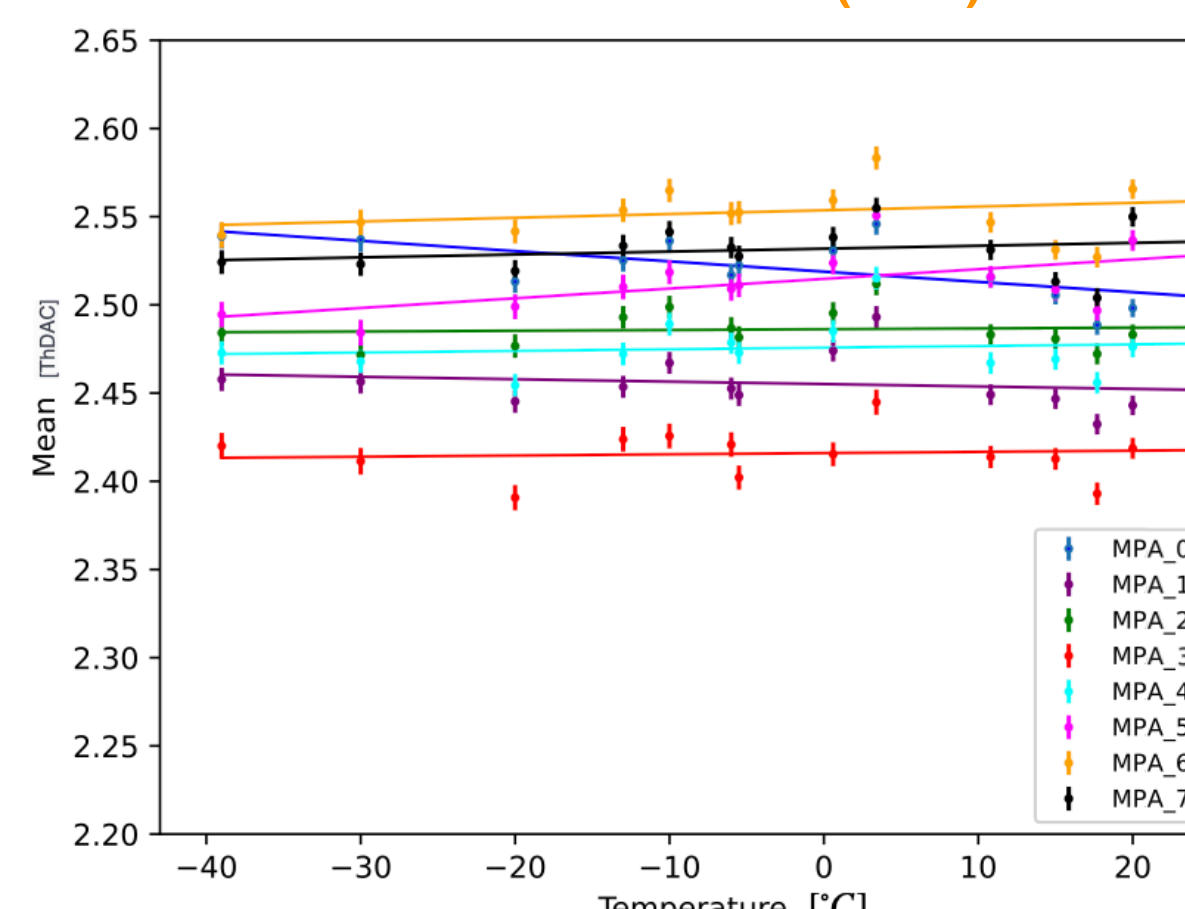
### Short Strip Asic (SSA)



The noise decreases in the SSA while the temperature decreases as expected

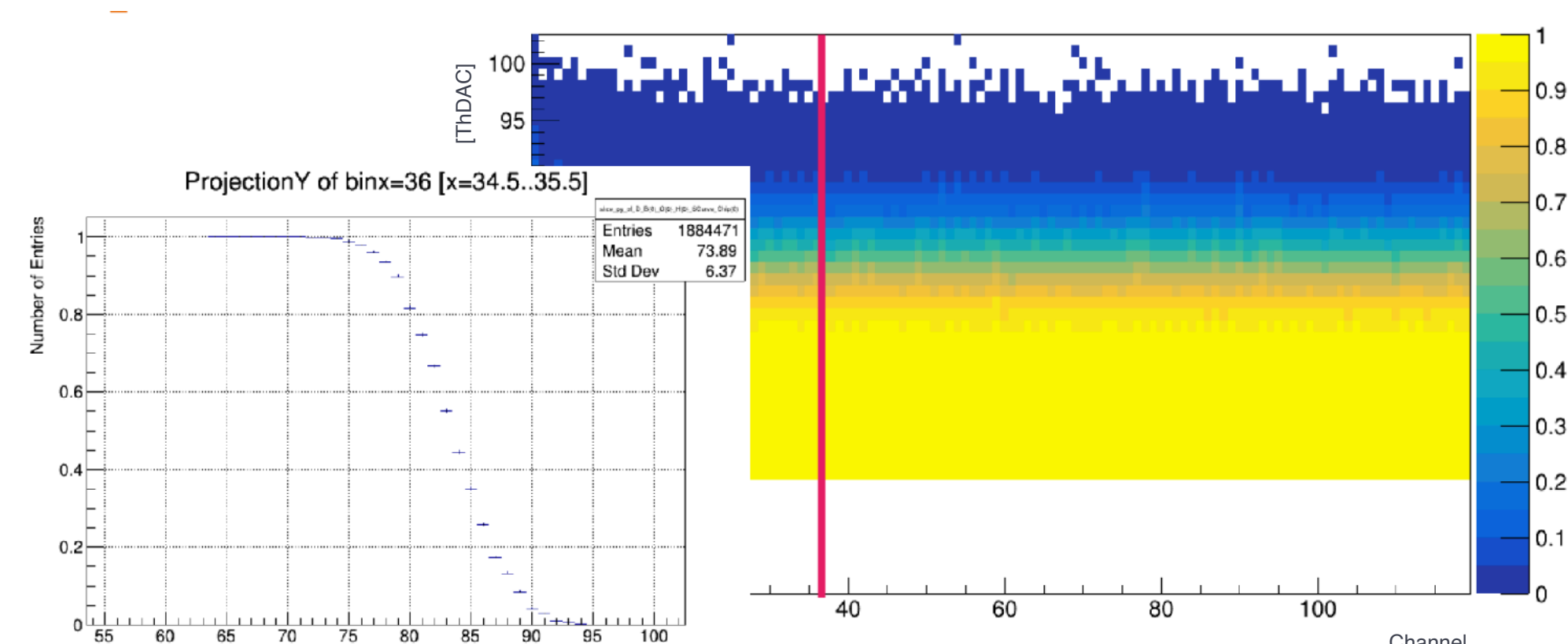
1 ThDAC = 0.040 fC = 250 electrons

### Macro Pixel Asic (MPA)



For the MPA, the noise is constant with respect to the temperature as expected

1 ThDAC = 0.015 fC = 94 electrons



Perform a so-called S-Curve (occupancy as a function of threshold measurement) and fit it for each channel with an error function

$$f(x) = \frac{1}{2} \operatorname{erf}\left(\frac{x - \mu}{\sqrt{2}\sigma}\right)$$

Extraction of the pedestal ( $\mu$ ) and the front-end channel noise ( $\sigma$ )

- HV Bias -300V
- Dew point between  $-54^\circ C$  to  $-58^\circ C$  in the carrier plate
- Temperatures from  $25^\circ C$  to  $-40^\circ C$  in the carrier plate

## Conclusions

- The Burn-in setup is usable for the first modules but not yet fully automated
- Temperature studies were performed showing good homogeneity with the power off and the expected behaviour when turning on and performing a measurement
- Noise measurements showed expected behaviour

## Next steps

- Extreme cold test of the module
- Optimization of the time needed to reach stablehand lower temperatures
- Automated temperature cycles measurement
- A full burn-in test (24h temperature cycle with noise measurements) of a functional module